Serial-in / Parallel-out Driver Series

4-input Serial-in / Parallel-out Drivers

BU2092F BU2092FV

Description

BU2092F/BU2092FV are an open drain output driver.It incorporates a built-in shift register and a latch circuit to turn on a maximum of 12 output by a 4-line interface, linked to a microcontroller.
An open drain output provides maximum 25mA current.

Key Specifications

- Power supply voltage range: 2.7V to 5.5V
- Output voltage: 0V to +25.0V
- Operating temperature range: -25℃ to +75℃

Features

- LED can be driven directly
- 12bit parallel output
- This product can be operated on low voltage

Package

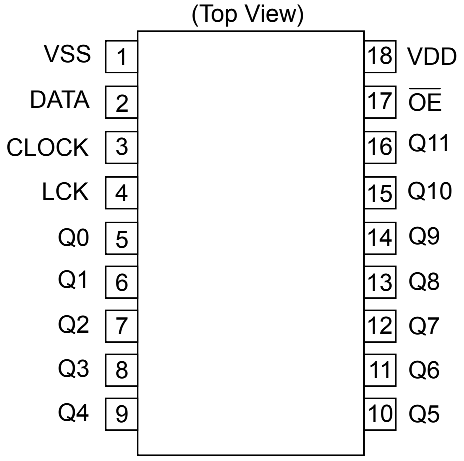
Package	W(Typ) x D(Typ) x H(Max)
SOP18	11.20mm x 7.80mm x 2.01mm
SSOP-B20	6.50mm x 6.40mm x 1.45mm

SOP18
BU2092F

SSOP-B20
BU2092FV

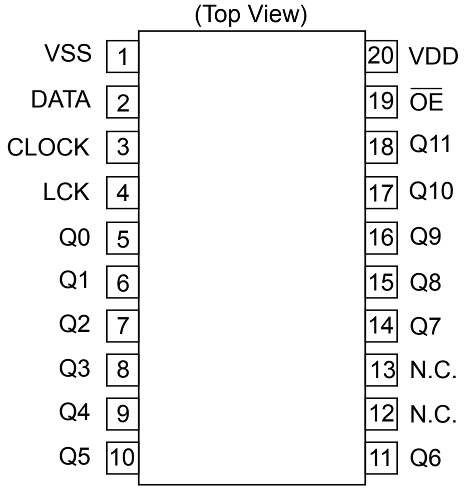
Pin Configurations

(Top View)



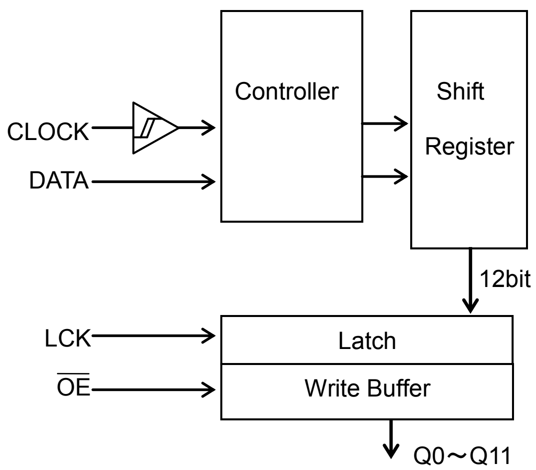
SOP18
BU2092F

(Top View)



SSOP-B20
BU2092FV

Block Diagrams



○Product structure：Silicon monolithic integrated circuit ○This product has not designed protection against radioactive rays

Pin Descriptions

BU2092F

<table>
<tr><th>Pin No.</th><th>Pin Name</th><th>I/O</th><th>Function</th></tr>
<tr><td>1</td><td>VSS</td><td>-</td><td>Ground</td></tr>
<tr><td>2</td><td>DATA</td><td>I</td><td>Serial Data Input</td></tr>
<tr><td>3</td><td>CLOCK</td><td>I</td><td>Shift clock of DATA (Rising Edge Trigger)</td></tr>
<tr><td>4</td><td>LCK</td><td>I</td><td>Latch clock of DATA (Rising Edge Trigger)</td></tr>
<tr><td>5</td><td>Q0</td><td rowspan="12">O</td><td rowspan="12">Parallel Data Output (Nch Open Drain)<table><tr><td>Latch Data</td><td>L</td><td>H</td></tr><tr><td>Output</td><td>ON</td><td>OFF</td></tr></table></td></tr>
<tr><td>6</td><td>Q1</td></tr>
<tr><td>7</td><td>Q2</td></tr>
<tr><td>8</td><td>Q3</td></tr>
<tr><td>9</td><td>Q4</td></tr>
<tr><td>10</td><td>Q5</td></tr>
<tr><td>11</td><td>Q6</td></tr>
<tr><td>12</td><td>Q7</td></tr>
<tr><td>13</td><td>Q8</td></tr>
<tr><td>14</td><td>Q9</td></tr>
<tr><td>15</td><td>Q10</td></tr>
<tr><td>16</td><td>Q11</td></tr>
<tr><td>17</td><td>$\overline{OE}$</td><td>I</td><td>Output Enable (“H” level : Output is OFF)</td></tr>
<tr><td>18</td><td>VDD</td><td>-</td><td>Power Supply</td></tr>
</table>

BU2092FV

<table>
<tr><th>Pin No.</th><th>Pin Name</th><th>I/O</th><th>Function</th></tr>
<tr><td>1</td><td>VSS</td><td>-</td><td>Ground</td></tr>
<tr><td>2</td><td>DATA</td><td>I</td><td>Serial Data Input</td></tr>
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<tr><td>6</td><td>Q1</td></tr>
<tr><td>7</td><td>Q2</td></tr>
<tr><td>8</td><td>Q3</td></tr>
<tr><td>9</td><td>Q4</td></tr>
<tr><td>10</td><td>Q5</td></tr>
<tr><td>11</td><td>Q6</td></tr>
<tr><td>12</td><td>N.C.</td><td>-</td><td>Non Connected</td></tr>
<tr><td>13</td><td>N.C.</td><td>-</td><td>Non Connected</td></tr>
<tr><td>14</td><td>Q7</td><td rowspan="5">O</td><td rowspan="5">Parallel Data Output (Nch Open Drain)<table><tr><td>Latch Data</td><td>L</td><td>H</td></tr><tr><td>Output</td><td>ON</td><td>OFF</td></tr></table></td></tr>
<tr><td>15</td><td>Q8</td></tr>
<tr><td>16</td><td>Q9</td></tr>
<tr><td>17</td><td>Q10</td></tr>
<tr><td>18</td><td>Q11</td></tr>
<tr><td>19</td><td>$\overline{OE}$</td><td>I</td><td>Output Enable (“H” level : Output is OFF)</td></tr>
<tr><td>20</td><td>VDD</td><td>-</td><td>Power Supply</td></tr>
</table>

Absolute Maximum Ratings

Parameter	Symbol	Limits		Unit
Supply Voltage	V_{DD}	-0.3 to +7.0		V
Input Voltage	V_{IN}	V_{SS}-0.3 to V_{DD}+0.3		V
Output Voltage	V_O	V_{SS} to +25.0		V
Operating Temperature	T_{opr}	-25 to +75		°C
Storage Temperature	T_{stg}	-55 to +125		°C
Power Dissipation	P_D	SOP18	0.55 (Note 1)	W
		SSOP-B20	0.65 (Note 2)	

(Note 1) Mounted on 70mm x 70mm x 1.6mm glass epoxy board. Reduce 5.5mW per 1°C above 25°C.
(Note 2) Mounted on 70mm x 70mm x 1.6mm glass epoxy board. Reduce 6.5mW per 1°C above 25°C.
Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions (T_A =25℃, V_{SS}=0V)

Parameter	Symbol	Limits	Unit
Supply Voltage	V_{DD}	+2.7 to +5.5	V
Output Voltage	V_O	0 to 25.0	V

Electrical Characteristics

DC Characteristics

(Unless otherwise specified, V_{DD}=5V, V_{SS}=0V, T_A =25℃)

Parameter	Symbol	Limits			Unit	Condition
		Min	Typ	Max		
Input high-level Voltage	V_{IH}	3.5	-	-	V	-
Input low-level Voltage	V_{IL}	-	-	1.5	V	-
Output low-level Voltage	V_{OL}	-	-	2.0	V	I_{OL}=20mA
Output high-level Leak Current	I_{IH}	-	-	10.0	µA	V_O=25.0V
Output low-level Leak Current	I_{IL}	-	-	-5.0	µA	V_O=0V
Quiescent Current	I_{DD}	-	-	5.0	µA	V_{IN}=V_{SS} or V_{DD} Q0 to Q11:OPEN

Electrical Characteristics - continued

Timing Characteristics
(Unless otherwise specified, V_{DD}=5V, V_{SS}=0V, T_A =25℃)

Parameter	Symbol	Limit			Unit		Condition
		Min	Typ	Max		VDD(V)	
Minimum Clock Pulse Width	t_w	1000	-	-	ns	3	-
		500	-	-	ns	5	
Minimum Latch Pulse Width (LCK)	t_w (LCK)	1000	-	-	ns	3	-
		500	-	-	ns	5	
Setup Time (LCK→CLOCK)	t_s	400	-	-	ns	3	-
		200	-	-	ns	5	
Setup Time (DATA→CLOCK)	t_{su}	400	-	-	ns	3	-
		200	-	-	ns	5	
Hold Time (CLOCK→DATA)	t_H	400	-	-	ns	3	-
		200	-	-	ns	5	
Propagation (LCK→OUTPUT Q_X)	t_{PLZ} (LCK)	-	90	-	ns	3	R_L=5kΩ C_L=10pF
		-	55	-	ns	5	
	t_{PZL} (LCK)	-	115	-	ns	3	R_L=5kΩ C_L=10pF
		-	50	-	ns	5	
Propagation ($\overline{OE}$ →OUTPUT Q_X)	t_{PLZ}	-	70	-	ns	3	R_L=5kΩ C_L=10pF
		-	45	-	ns	5	
	t_{PZL}	-	80	-	ns	3	R_L=5kΩ C_L=10pF
		-	35	-	ns	5	

Waveform of Timing Characteristics

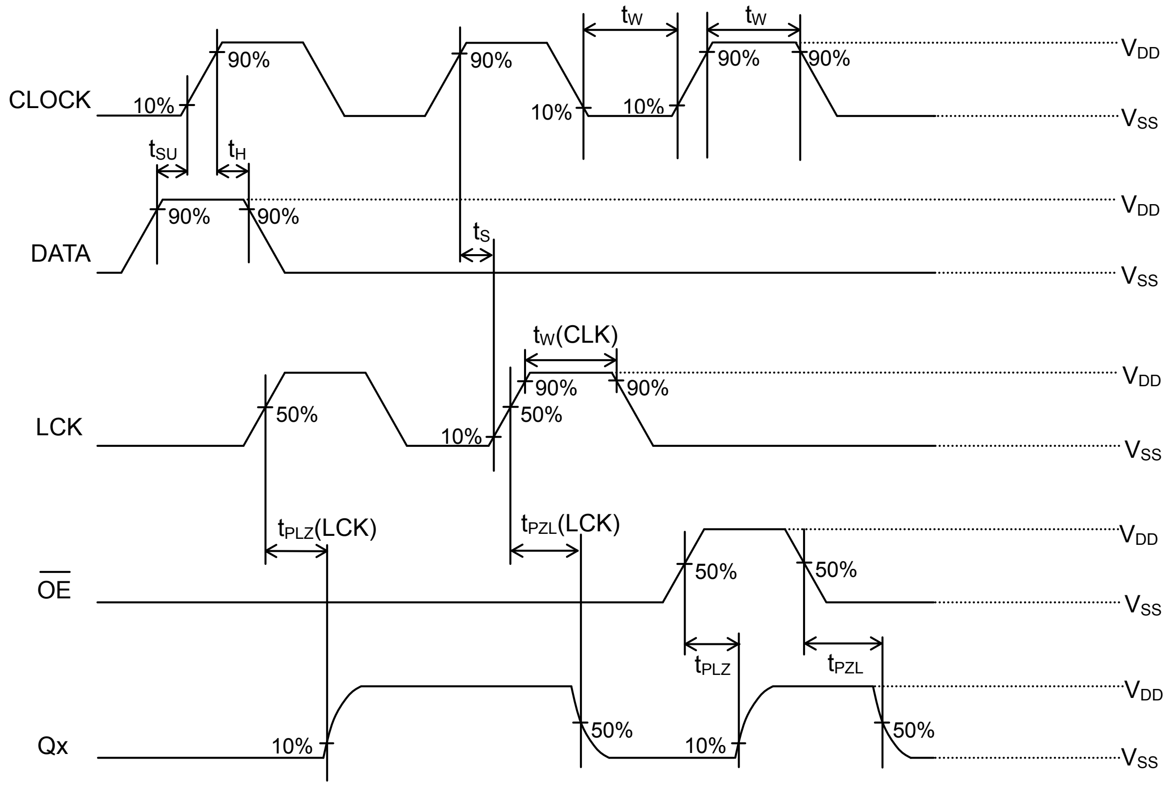


Figure 1. Waveform of Timing Characteristics

Test Circuits (Figures are in case of BU2092F)

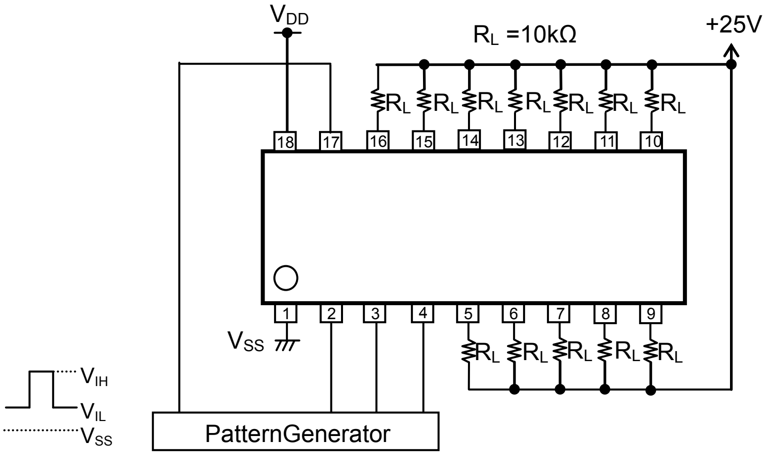


Figure 2. Test Circuit of Input H/LVoltage

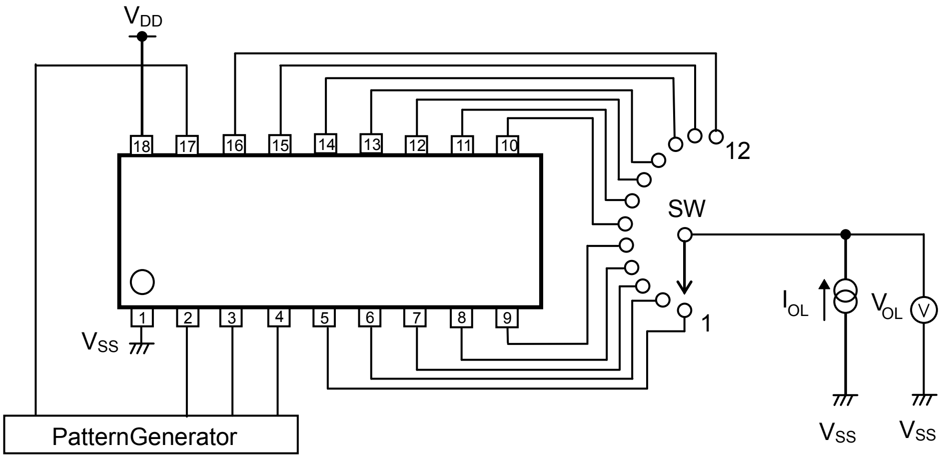


Figure 3. Test Circuit of Output L Voltage

Test Circuits - continued (Figures are in case of BU2092F)

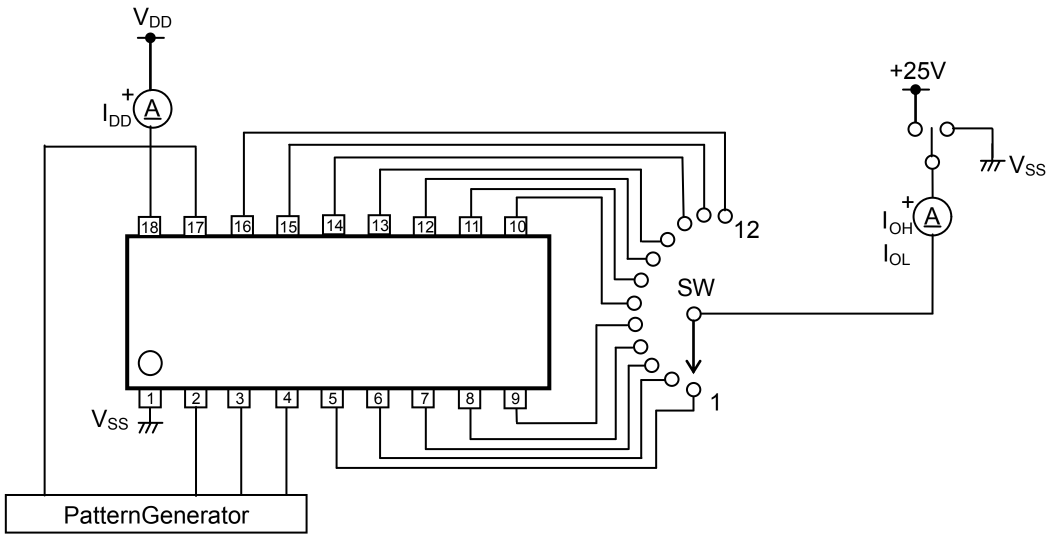


Figure 4. Test Circuit of Output H/L Leak / Static Dissipation Current

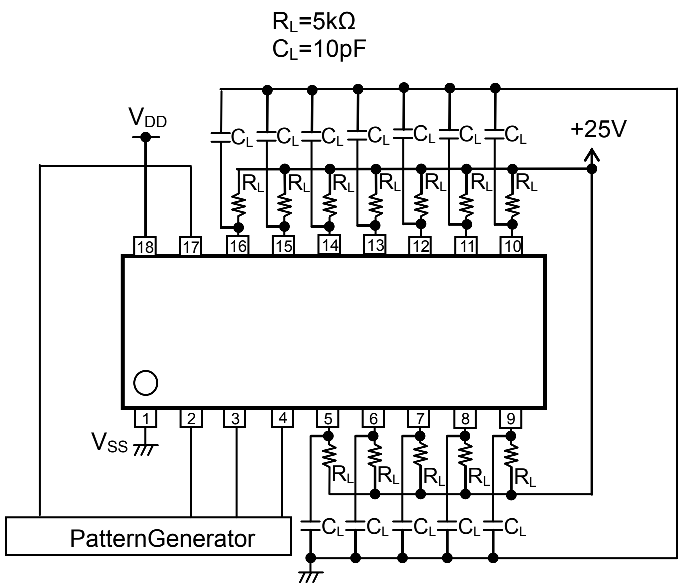
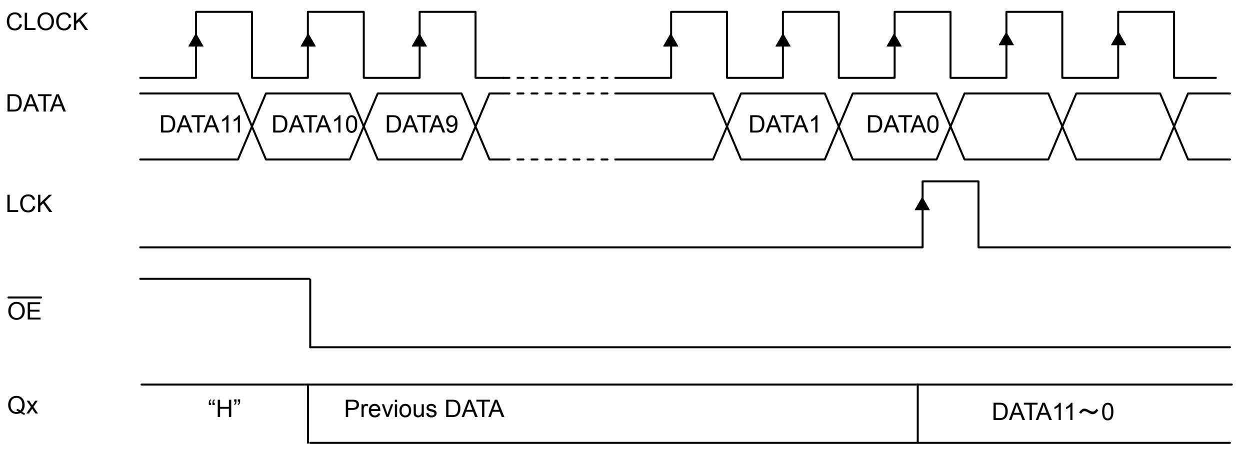


Figure 5. Test Circuit of Timing Characteristics

Timing Chart



(Note3) Diagram shows a status where a pull-up resistor is connected to output.

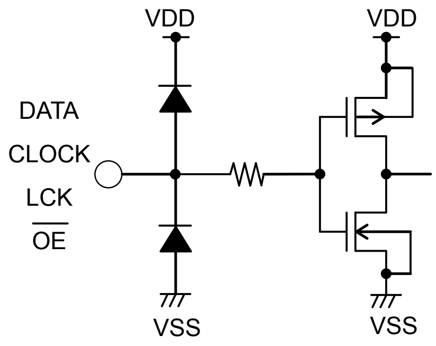
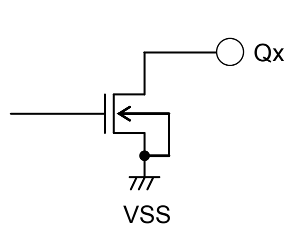
Figure 6 . Timing Chart

1. After the power is turned on and the voltage is stabilized, LCK should be activated, after clocking 12 data bits into the DATA terminal.
2. Qx parallel output data of the shift register is set after the 12th clock by the LCK.
3. Since the LCK is a label latch, data is retained in the "L" section and renewed in the "H" section of the LCK.
4. Data retained in the internal latch circuit is output when the $\overline{\text{OE}}$ is in the "L" section.

［Truth Table］

Input				Function
CLOCK	DATA	LCK	$\overline{\text{OE}}$	
×	×	×	H	Output (Q0 to Q11) Disable
×	×	×	L	Output (Q0 to Q11) Enable
↑	L	×	×	Store "L" in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
↑	H	×	×	Store "H" in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
↓	×	×	×	The data of shift register has no change.
×	×	↑	×	The data of shift register is transferred to the storage register.
×	×	↓	×	The data of storage register has no change.

I/O Equivalence Circuits

DATA,CLOCK,LCK,$\overline{\text{OE}}$	Q0 to Q11
	

Power Dissipation

Power dissipation(total loss) indicates the power that can be consumed by IC at T_A=25°C(normal temperature). IC is heated when it consumed power, and the temperature of IC chip becomes higher than ambient temperature. The temperature that can be accepted by IC chip depends on circuit configuration, manufacturing process, and consumable power is limited. Power dissipation is determined by the temperature allowed in IC chip(maximum junction temperature) and thermal resistance of package(heat dissipation capability). The maximum junction temperature is typically equal to the maximum value in the storage temperature range. Heat generated by consumed power of IC radiates from the mold resin or lead frame of the package. The parameter which indicates this heat dissipation capability(hardness of heat release)is called thermal resistance, represented by the symbol θ_{JA} (°C/W).The temperature of IC inside the package can be estimated by this thermal resistance. Figure 7 shows the model of thermal resistance of the package. Thermal resistance θ_{JA}, ambient temperature T_A, maximum junction temperature T_{Jmax}, and power dissipation P_D can be calculated by the equation below:

$$\theta_{JA} = (T_{Jmax} - T_A) / P_D \quad (°C/W)$$

Derating curve in Figure 8 indicates power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC begins to attenuate at certain ambient temperature. This gradient is determined by thermal resistance θ_{JA}. Thermal resistance θ_{JA} depends on chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition.

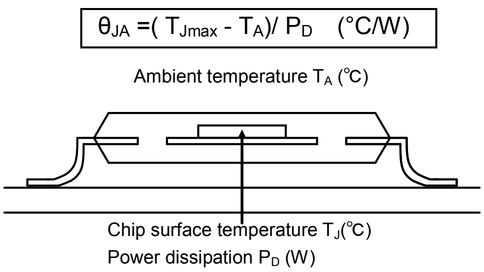


Figure 7. Thermal resistance

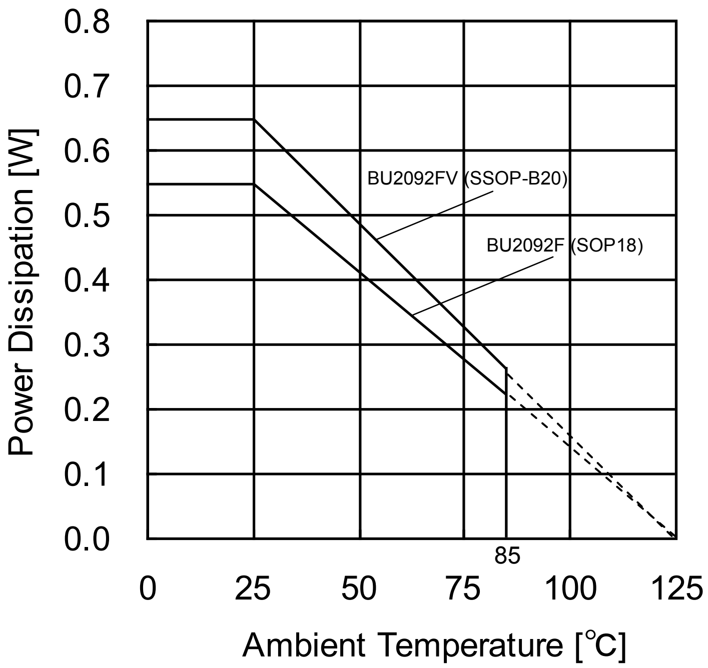


Figure 8. Derating Curve

Operational Notes

1. **Reverse Connection of Power Supply**
   Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. **Power Supply Lines**
   Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. **Ground Voltage**
   Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. **Ground Wiring Pattern**
   When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. **Thermal Consideration**
   Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. **Recommended Operating Conditions**
   These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. **Inrush Current**
   When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. **Operation Under Strong Electromagnetic Field**
   Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. **Testing on Application Boards**
   When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. **Inter-pin Short and Mounting Errors**
    Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. **Unused Input Pins**
    Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

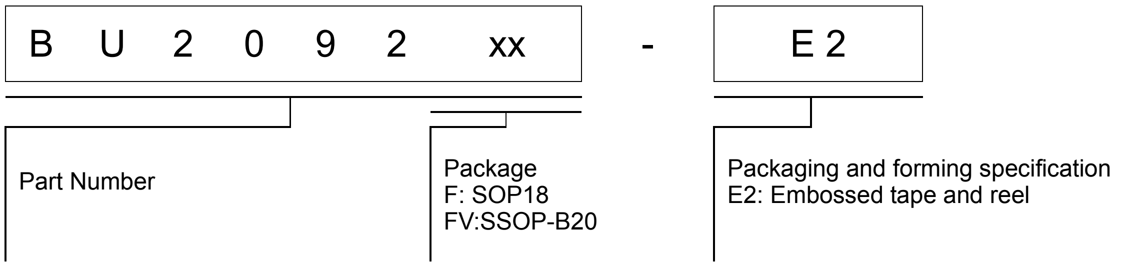
Operational Notes – continued

12. Regarding the Input Pin of the IC
In the construction of this IC, P-N junctions are inevitably formed creating parasitic diodes or transistors. The operation of these parasitic elements can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions which cause these parasitic elements to operate, such as applying a voltage to an input pin lower than the ground voltage should be avoided. Furthermore, do not apply a voltage to the input pins when no power supply voltage is applied to the IC. Even if the power supply voltage is applied, make sure that the input pins have voltages within the values specified in the electrical characteristics of this IC.

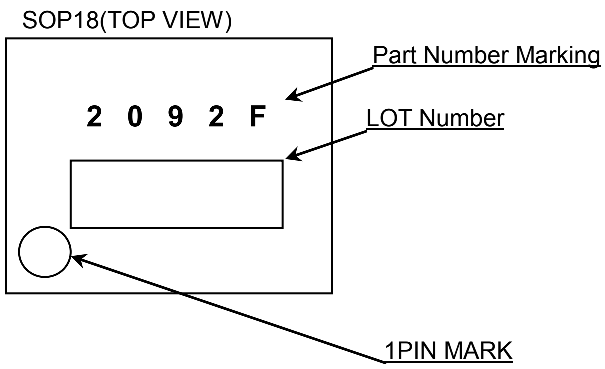
13. Ceramic Capacitor
When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

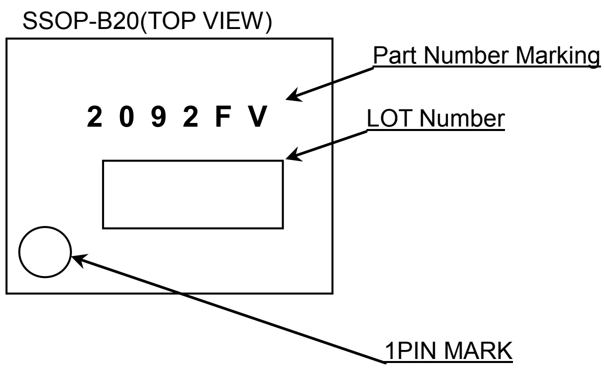
14. Area of Safe Operation (ASO)
Operate the IC such that the output voltage, output current, and power dissipation are all within the Area of Safe Operation (ASO).

Ordering Information



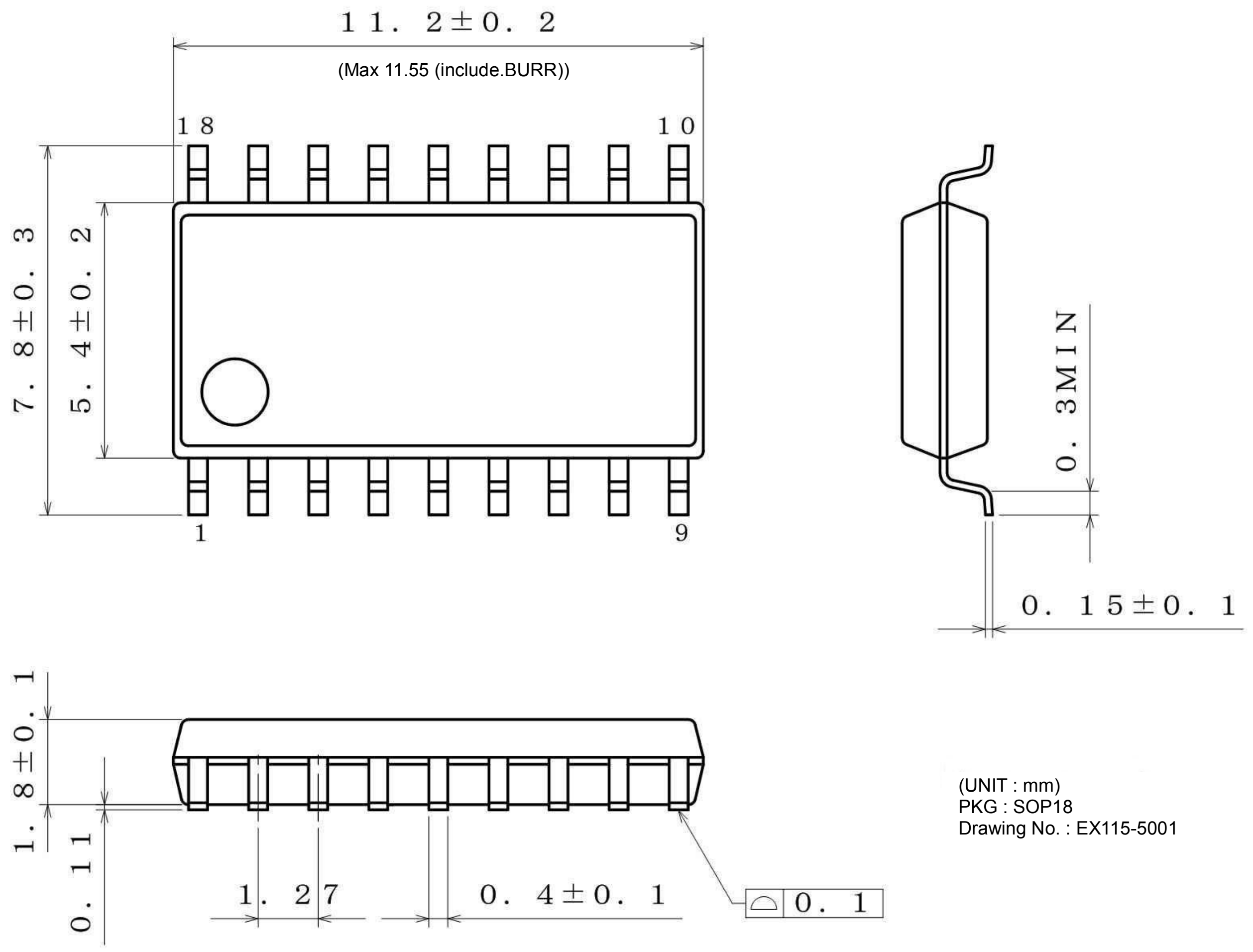
Marking Diagrams





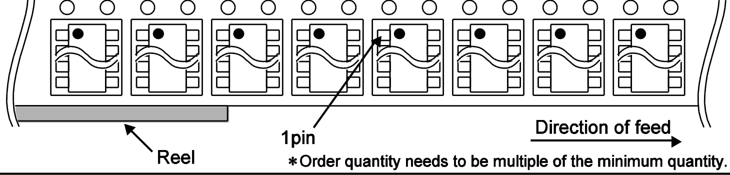
Physical Dimension, Tape and Reel Information

Package Name	SOP18



<Tape and Reel information>

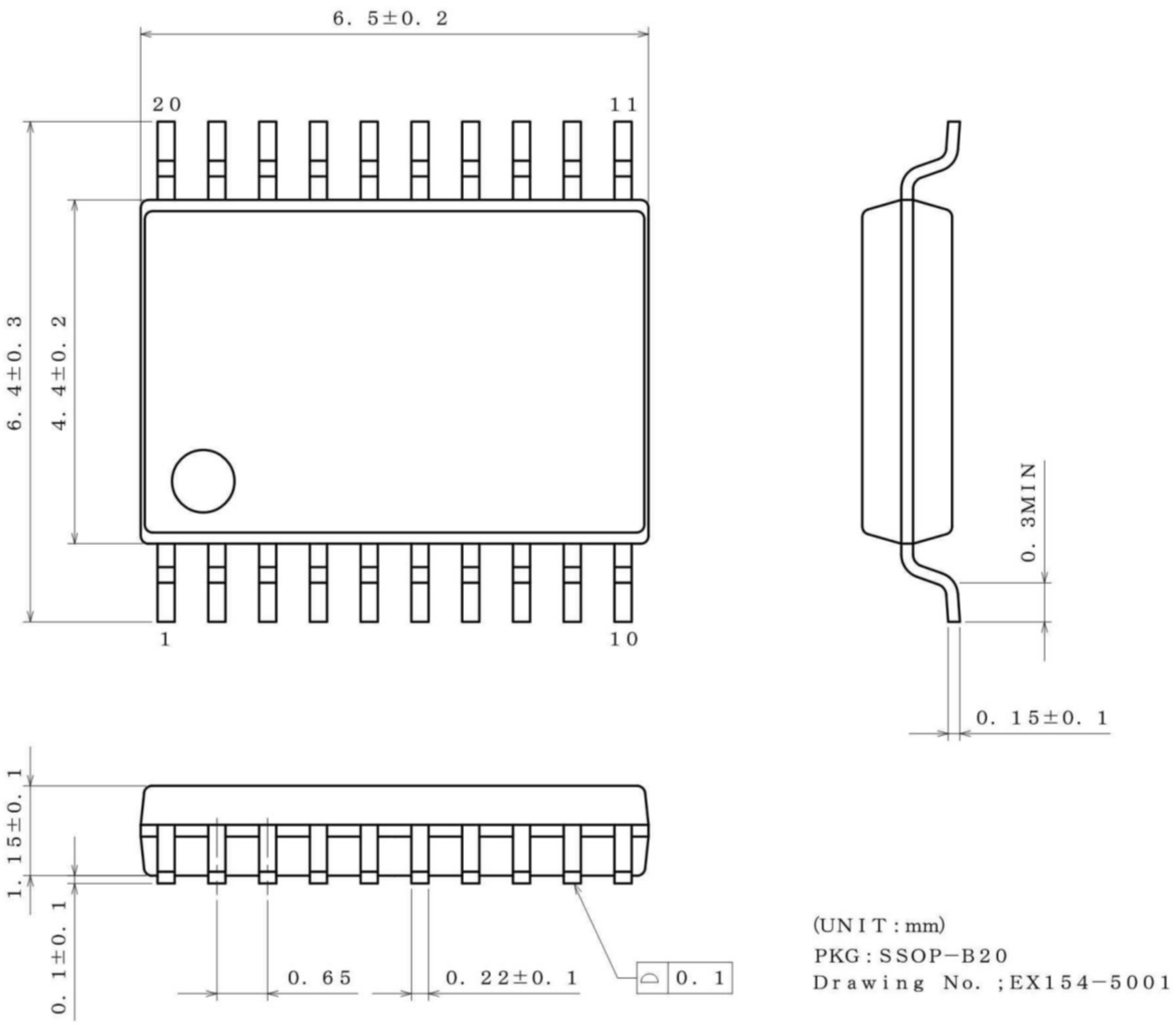
Tape	Embossed carrier tape
Quantity	2000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



∗Order quantity needs to be multiple of the minimum quantity.

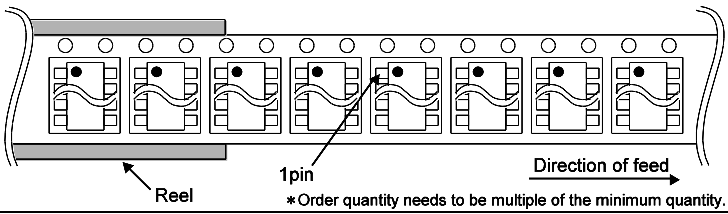
Physical Dimension, Tape and Reel Information– continued

Package Name	SSOP-B20



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



∗Order quantity needs to be multiple of the minimum quantity.

Revision History

Date	Revision	Changes
22.Nov.2013	001	New Release
18.Sep.2015	002	Page.1 Key Specifications Operating temperature range: -40℃ to +85℃ -> -25℃ to +75℃

Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
   [a] Installation of protection circuits or other protective devices to improve system safety
   [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
   [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   - [b] the temperature or humidity exceeds those recommended by ROHM
   - [c] the Products are exposed to direct sunshine or condensation
   - [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

Precaution Regarding Intellectual Property Rights

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General Precaution

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